



# SGM895/SGM896/SGM897/SGM898/SGM899

## Ultra-Small, Supervisory Circuits with Adjustable Sequencing

### GENERAL DESCRIPTION

The SGM895/SGM896/SGM897/SGM898/SGM899 are ultra-small, low-power and high-accuracy micro-processor supervisory circuits with adjustable sequencing capability. Since the high-impedance detection input pin (IN) with a 0.5V threshold voltage is separated from the power supply, these devices provide great flexibility with adjustable thresholds by using an external resistive divider. Moreover, the delay time can be adjusted by an external capacitor connected to the CDELAY pin. The devices are suitable for some power sequencing, reset sequencing and power-switching equipment.

When the input voltage at IN ( $V_{IN}$ ) exceeds the  $V_{TH}$  threshold voltage (0.5V, TYP) and the ENABLE input is high (or nENABLE is low), the OUT is high (or nOUT is low). When  $V_{IN}$  is lower than  $V_{TL}$  (0.495V, TYP) or when the ENABLE input is low (or nENABLE is high), the OUT is low (or nOUT is high). The devices all have a capacitor-adjustable input delay time ( $t_{DELAY}$ ) between  $V_{IN}$  greater than  $V_{TH}$  and the output assertion. The SGM89\_A has a capacitor-adjustable enable output delay time while the SGM89\_P has a 350ns (TYP) fixed delay time.

All devices are available in ultra-small Green UTDFN-1.45×1-6AL and TSOT-23-6 packages.

### FEATURES

- **High Voltage Threshold Accuracy:**
  - ♦ +25°C: ±1%
  - ♦ -40°C to +125°C: ±1.6%
- **Low Power Consumption: 2.1µA (TYP)**
- **Operating Supply Voltage Range: 1.6V to 5.5V**
- **Capacitor-Adjustable Delay**
- **Enable Input Options:**
  - ♦ **Active-High: SGM895 and SGM897**
  - ♦ **Active-Low: SGM896, SGM898 and SGM899**
- **Output Options:**
  - ♦ **Active-High Push-Pull: SGM895 and SGM899**
  - ♦ **Active-Low Push-Pull: SGM896**
  - ♦ **Active-High Open-Drain (28V Tolerant): SGM897**
  - ♦ **Active-Low Open-Drain (28V Tolerant): SGM898**
- **Available in Ultra-Small Green UTDFN-1.45×1-6AL and TSOT-23-6 Packages**

### APPLICATIONS

Portable Equipment  
Computers  
µC Power Monitoring  
Automotive Applications  
Medical Equipment  
Intelligent Instruments

### TYPICAL APPLICATION

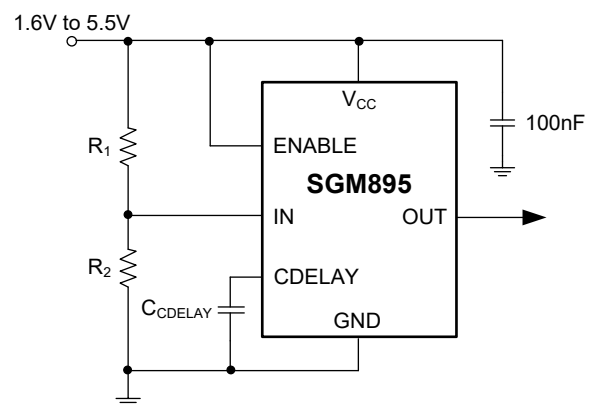


Figure 1. Typical Application Circuit of SGM895

**PACKAGE/ORDERING INFORMATION**

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM895A	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM895AXUDL6G/TR	J9X	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM895AXTN6G/TR	CICXX	Tape and Reel, 3000
SGM895P	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM895PXUDL6G/TR	IAX	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM895PXTN6G/TR	CKFXX	Tape and Reel, 3000
SGM896A	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM896AXUDL6G/TR	QBX	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM896AXTN6G/TR	CL0XX	Tape and Reel, 3000
SGM896P	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM896PXUDL6G/TR	QCX	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM896PXTN6G/TR	CL1XX	Tape and Reel, 3000
SGM897A	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM897AXUDL6G/TR	I8X	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM897AXTN6G/TR	CIDXX	Tape and Reel, 3000
SGM897P	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM897PXUDL6G/TR	IBX	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM897PXTN6G/TR	CL2XX	Tape and Reel, 3000
SGM898A	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM898AXUDL6G/TR	QDX	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM898AXTN6G/TR	CL3XX	Tape and Reel, 3000
SGM898P	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM898PXUDL6G/TR	QEX	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM898PXTN6G/TR	CL4XX	Tape and Reel, 3000
SGM899A	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM899AXUDL6G/TR	I9X	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM899AXTN6G/TR	CIEXX	Tape and Reel, 3000
SGM899P	UTDFN-1.45×1-6AL	-40°C to +125°C	SGM899PXUDL6G/TR	ICX	Tape and Reel, 5000
	TSOT-23-6	-40°C to +125°C	SGM899PXTN6G/TR	CL5XX	Tape and Reel, 3000

**MARKING INFORMATION**

NOTE: X = Date Code. XX = Date Code

**UTDFN-1.45×1-6AL**

**YY X**

— Date Code - Quarter  
 — Serial Number

**TSOT-23-6**

**YYY X X**

— Date Code - Week  
 — Date Code - Year  
 — Serial Number

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

**ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> , ENABLE, nENABLE, IN .....	-0.3V to 6V
OUT, nOUT (Push-Pull) .....	-0.3V to V <sub>CC</sub> + 0.3V
OUT, nOUT (Open-Drain) .....	-0.3V to 30V
CDELAY.....	-0.3V to V <sub>CC</sub> + 0.3V
Output Current (All Pins).....	±20mA
Package Thermal Resistance	
UTDFN-1.45×1-6AL, θ <sub>JA</sub> .....	294°C/W
TSOT-23-6, θ <sub>JA</sub> .....	230°C/W
Junction Temperature.....	+150°C
Storage Temperature Range .....	-65°C to +150°C
Lead Temperature (Soldering, 10s).....	+260°C
ESD Susceptibility	
HBM.....	4000V
CDM .....	1000V

**RECOMMENDED OPERATING CONDITIONS**

Operating Junction Temperature Range .....	-40°C to +125°C
Operating Ambient Temperature Range.....	-40°C to +125°C

**OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

**ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

**DISCLAIMER**

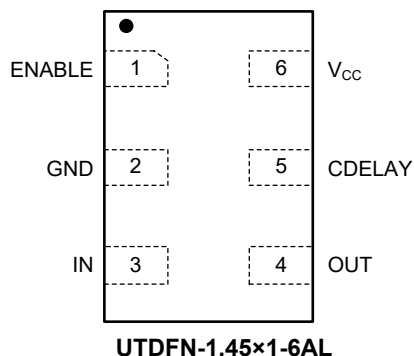
SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

**SELECTOR GUIDE**

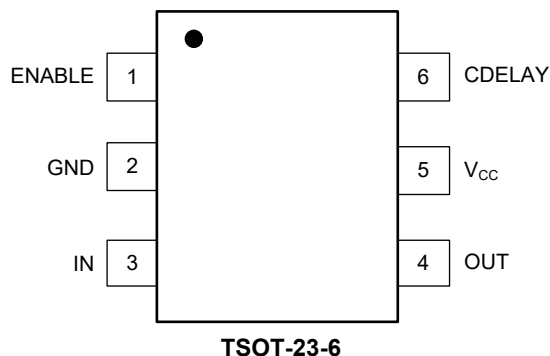
DEVICE	ENABLE INPUT	OUTPUT	INPUT DELAY TIME	ENABLE DELAY TIME
SGM895A	Active-High	Active-High, Push-Pull	Capacitor-Adjustable	Capacitor-Adjustable
SGM895P	Active-High	Active-High, Push-Pull	Capacitor-Adjustable	350ns Delay
SGM896A	Active-Low	Active-Low, Push-Pull	Capacitor-Adjustable	Capacitor-Adjustable
SGM896P	Active-Low	Active-Low, Push-Pull	Capacitor-Adjustable	350ns Delay
SGM897A	Active-High	Active-High, Open-Drain	Capacitor-Adjustable	Capacitor-Adjustable
SGM897P	Active-High	Active-High, Open-Drain	Capacitor-Adjustable	350ns Delay
SGM898A	Active-Low	Active-Low, Open-Drain	Capacitor-Adjustable	Capacitor-Adjustable
SGM898P	Active-Low	Active-Low, Open-Drain	Capacitor-Adjustable	350ns Delay
SGM899A	Active-Low	Active-High, Push-Pull	Capacitor-Adjustable	Capacitor-Adjustable
SGM899P	Active-Low	Active-High, Push-Pull	Capacitor-Adjustable	350ns Delay

**PIN CONFIGURATIONS**

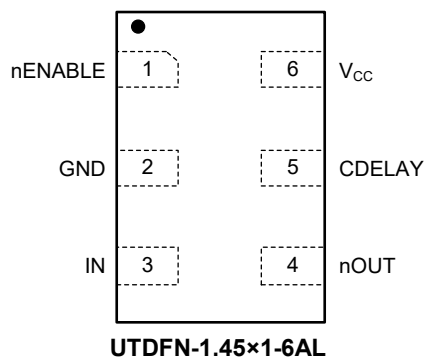
**SGM895/SGM897 (TOP VIEW)**



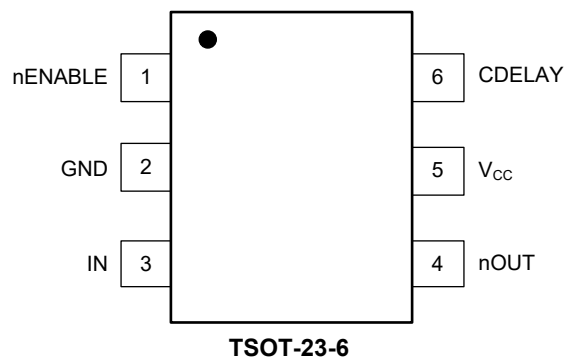
**SGM895/SGM897 (TOP VIEW)**



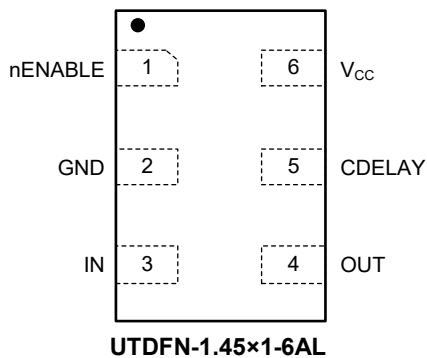
**SGM896/SGM898 (TOP VIEW)**



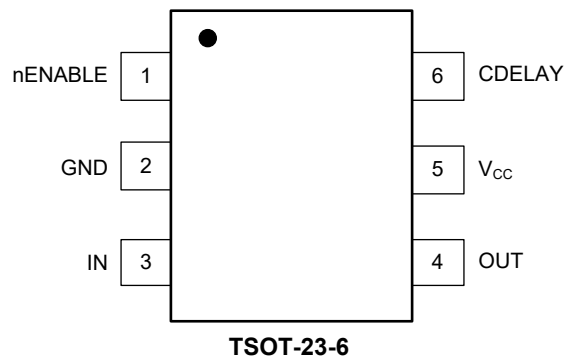
**SGM896/SGM898 (TOP VIEW)**



**SGM899 (TOP VIEW)**



**SGM899 (TOP VIEW)**



**PIN DESCRIPTION**

PIN						NAME	FUNCTION
SGM895/SGM897		SGM896/SGM898		SGM899			
UTDFN- 1.45×1-6AL	TSOT- 23-6	UTDFN- 1.45×1-6AL	TSOT- 23-6	UTDFN- 1.45×1-6AL	TSOT- 23-6		
1	1	—	—	—	—	ENABLE	Active-High Enable Input Pin. If ENABLE is set to low, the output will immediately enter into false state (OUT is low or nOUT is high) regardless of $V_{IN}$ . If $V_{IN}$ exceeds $V_{TH}$ , the output will enter into true state (OUT is high or nOUT is low) by setting ENABLE high after the enable output delay time (adjustable delay time for the SGM89_A and 350ns delay time for the SGM89_P).
—	—	1	1	1	1	nENABLE	Active-Low Enable Input Pin. If nENABLE is set to high, the output will immediately enter into false state (OUT is low or nOUT is high) regardless of $V_{IN}$ . If $V_{IN}$ exceeds $V_{TH}$ , the output will enter into true state (OUT is high or nOUT is low) by setting nENABLE low after the enable output delay time (adjustable delay time for the SGM89_A and 350ns delay time for the SGM89_P).
2	2	2	2	2	2	GND	Ground.
3	3	3	3	3	3	IN	High-Impedance Detection Input. The detection threshold can be adjusted by an external resistive divider connected to IN pin. The output state changes when $V_{IN}$ exceeds $V_{TH}$ (0.5V, TYP) or when $V_{IN}$ drops below $V_{TL}$ (0.495V, TYP).
4	4	—	—	4	4	OUT	Active-High, Push-Pull (SGM895/SGM899) or Open-Drain (SGM897) Output Pin. And the open-drain output needs a pull-up resistor. The OUT is logic low when the enable input is in the false state (ENABLE is low or nENABLE is high) or when $V_{IN}$ drops below $V_{TL}$ (0.495V, TYP). The OUT is logic high after the CDELAY adjustable delay period when the enable input is in the true state (ENABLE is high or nENABLE is low) and $V_{IN}$ exceeds $V_{TH}$ .
—	—	4	4	—	—	nOUT	Active-Low, Push-Pull (SGM896) or Open-Drain (SGM898) Output Pin. And the open-drain output needs a pull-up resistor. The nOUT is logic high when the enable input is in the false state (ENABLE is low or nENABLE is high) or when $V_{IN}$ drops below $V_{TL}$ (0.495V, TYP). The nOUT is logic low after the CDELAY adjustable delay period when the enable input is in the true state (ENABLE is high or nENABLE is low) and $V_{IN}$ exceeds $V_{TH}$ .
5	6	5	6	5	6	CDELAY	Capacitor-Adjustable Delay. The delay time can be set by an external capacitor ( $C_{CDELAY}$ ) between CDELAY and GND. $t_{DELAY} (ms) = 3.95 \times C_{CDELAY} (nF) + 0.048ms$ There is a 50 $\mu s$ (TYP) fixed delay for the output deasserting when $V_{IN}$ falls below $V_{TL}$ .
6	5	6	5	6	5	$V_{CC}$	Supply Voltage.

## ELECTRICAL CHARACTERISTICS

( $V_{CC} = 1.6V$  to  $5.5V$ , Full =  $-40^{\circ}C$  to  $+125^{\circ}C$ , typical values are at  $V_{CC} = 3.3V$  and  $T_J = +25^{\circ}C$ , unless otherwise noted.)

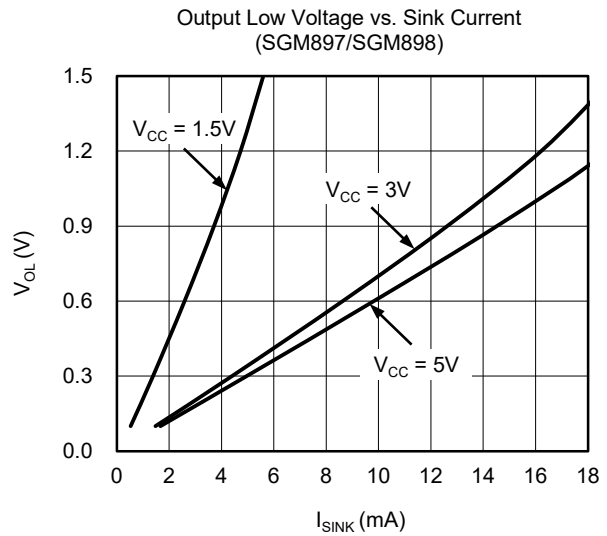
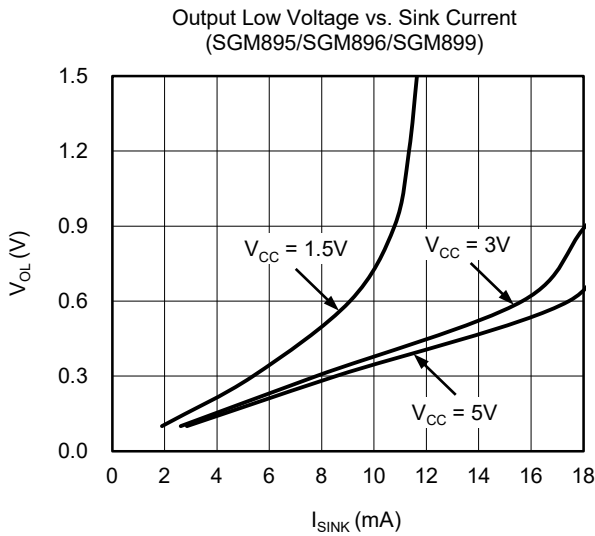
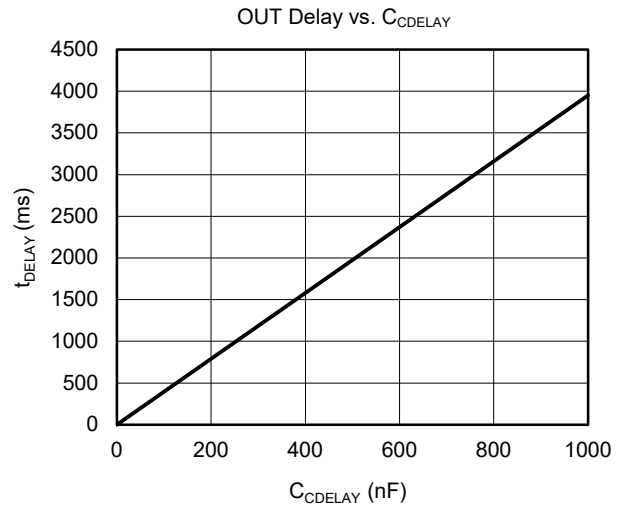
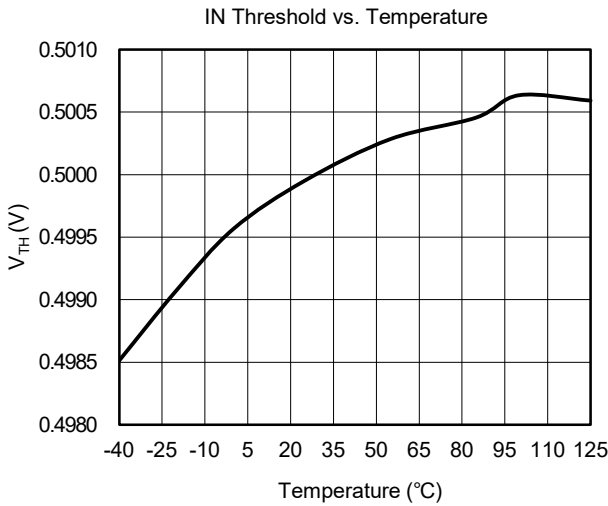
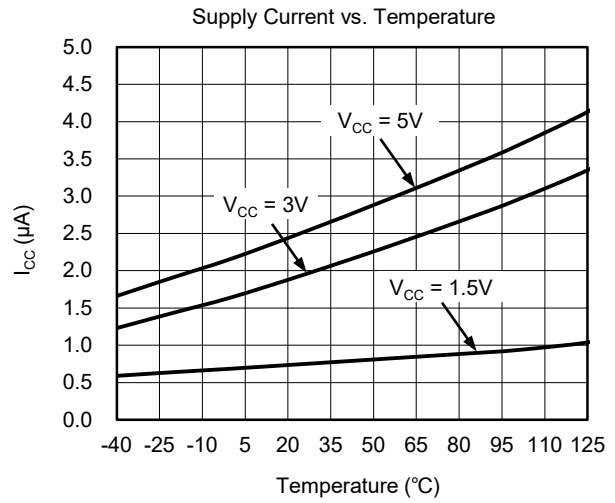
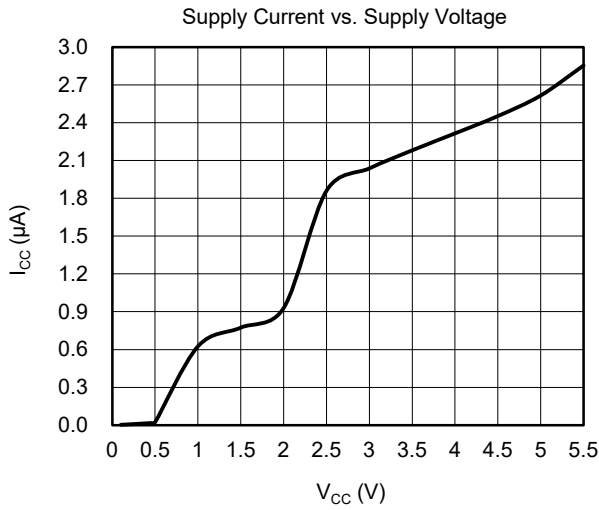
PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
<b>Supply</b>							
Operating Voltage Range	$V_{CC}$		Full	1.6		5.5	V
Under-Voltage Lockout <sup>(1)</sup>	$V_{UVLO}$	$V_{CC}$ falling	Full	1.31		1.49	V
$V_{CC}$ Supply Current	$I_{CC}$		Full		2.1	7.8	$\mu A$
<b>IN</b>							
Rising Threshold Voltage	$V_{TH}$	$V_{IN}$ rising, $1.6V < V_{CC} < 5.5V$	+25°C	0.495	0.500	0.505	V
			Full	0.492	0.500	0.508	
Falling Threshold Voltage	$V_{TL}$	$V_{IN}$ falling, $1.6V < V_{CC} < 5.5V$	+25°C	0.489	0.495	0.501	V
			Full	0.487	0.495	0.503	
Hysteresis	$V_{HYST}$	$V_{IN}$ falling	Full		5		mV
Input Current	$I_{IN}$	$V_{IN} = 0V$ or $V_{CC}$	Full	-20		20	nA
<b>CDELAY</b>							
Delay Charge Current	$I_{CD}$		Full	210	253	290	nA
Delay Threshold	$V_{TCD}$	CDELAY rising	Full	0.96	1.00	1.04	V
CDELAY Pull-Down Resistance	$R_{CDELAY}$		Full		120	350	$\Omega$
<b>ENABLE/nENABLE</b>							
Input Low Voltage	$V_{IL}$		Full			0.4	V
Input High Voltage	$V_{IH}$		Full	1.4			V
Input Leakage Current	$I_{LEAK}$	ENABLE, nENABLE = $V_{CC}$ or GND	Full	-50		50	nA
<b>OUT/nOUT</b>							
Output Low Voltage (Open-Drain or Push-Pull)	$V_{OL}$	$V_{CC} \geq 1.2V$ , $I_{SINK} = 90\mu A$ , SGM895/SGM897/SGM899 only	Full			0.3	V
		$V_{CC} \geq 2.25V$ , $I_{SINK} = 0.5mA$	Full			0.3	
		$V_{CC} \geq 4.5V$ , $I_{SINK} = 1mA$	Full			0.4	
Output High Voltage (Push-Pull)	$V_{OH}$	$V_{CC} \geq 2.25V$ , $I_{SOURCE} = 500\mu A$	Full	$0.8 \times V_{CC}$			V
		$V_{CC} \geq 4.5V$ , $I_{SOURCE} = 800\mu A$	Full	$0.8 \times V_{CC}$			
Output Open-Drain Leakage Current	$I_{LKG}$	Output high impedance, $V_{OUT} = 28V$	Full			1	$\mu A$
<b>Timing</b>							
IN to OUT/nOUT Propagation Delay	$t_{DELAY}$	$V_{IN}$ rising	$C_{CDELAY} = 0nF$	Full		48	$\mu s$
			$C_{CDELAY} = 47nF$	Full		185	ms
	$t_{DL}$	$V_{IN}$ falling	Full		50	$\mu s$	
ENABLE/nENABLE Minimum Input Pulse Width	$t_{PW}$		Full	1.1			$\mu s$
ENABLE/nENABLE Glitch Rejection			Full		210		ns
ENABLE/nENABLE to OUT/nOUT Delay	$t_{OFF}$	From device enabled to device disabled	Full		350		ns
ENABLE/nENABLE to OUT/nOUT Delay	$t_{PROPP}$	From device disabled to device enabled (SGM89_P)	Full		350		ns
		From device disabled to device enabled (SGM89_A)	$C_{CDELAY} = 0nF$	Full		30	$\mu s$
	$C_{CDELAY} = 47nF$		Full		185	ms	

**NOTES:**

1. If  $V_{CC}$  is lower than  $V_{UVLO}$ , the OUT will be low (or nOUT will be high).
2. The output state is not guaranteed if  $V_{CC}$  is lower than 1.2V.
3. In the initial power-on phase,  $V_{CC}$  must be greater than 1.6V and no less than 2ms to ensure correct output state.

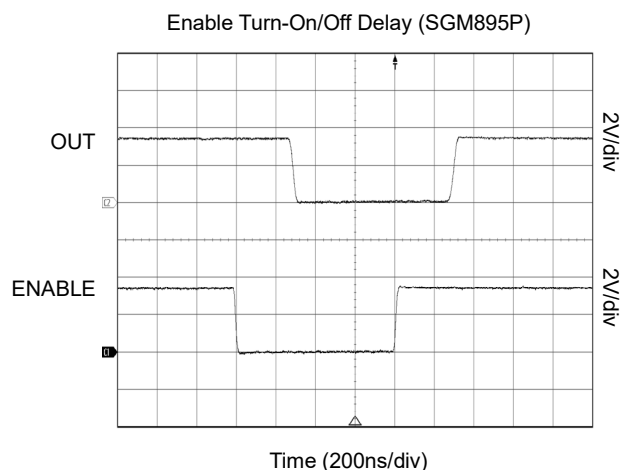
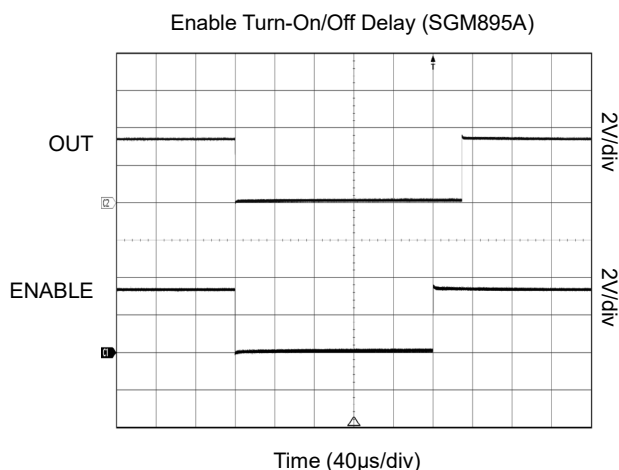
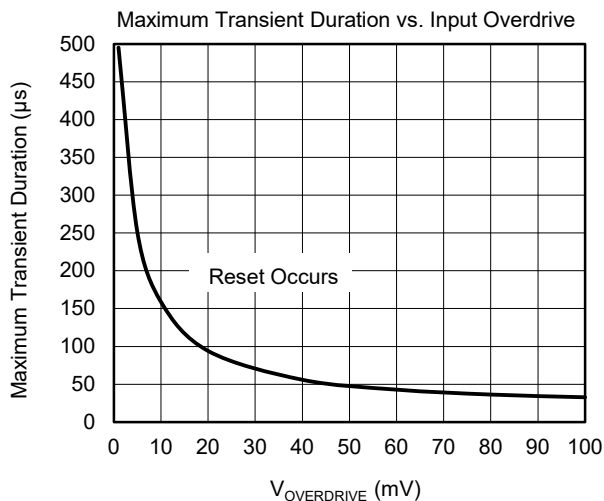
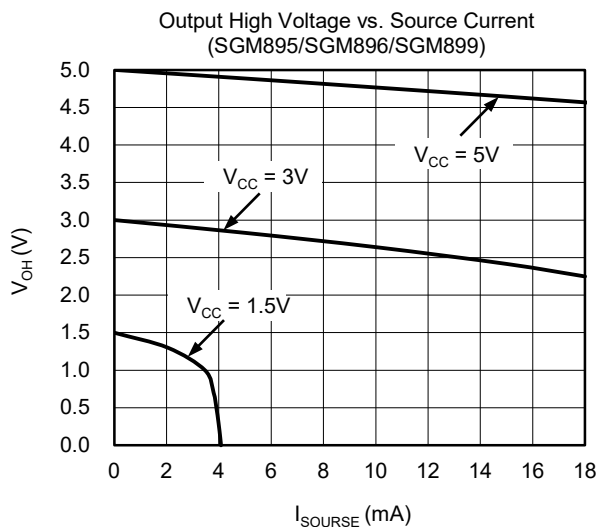
**TYPICAL PERFORMANCE CHARACTERISTICS**

$V_{CC} = 3.3V$  and  $T_J = +25^\circ C$ , unless otherwise noted.



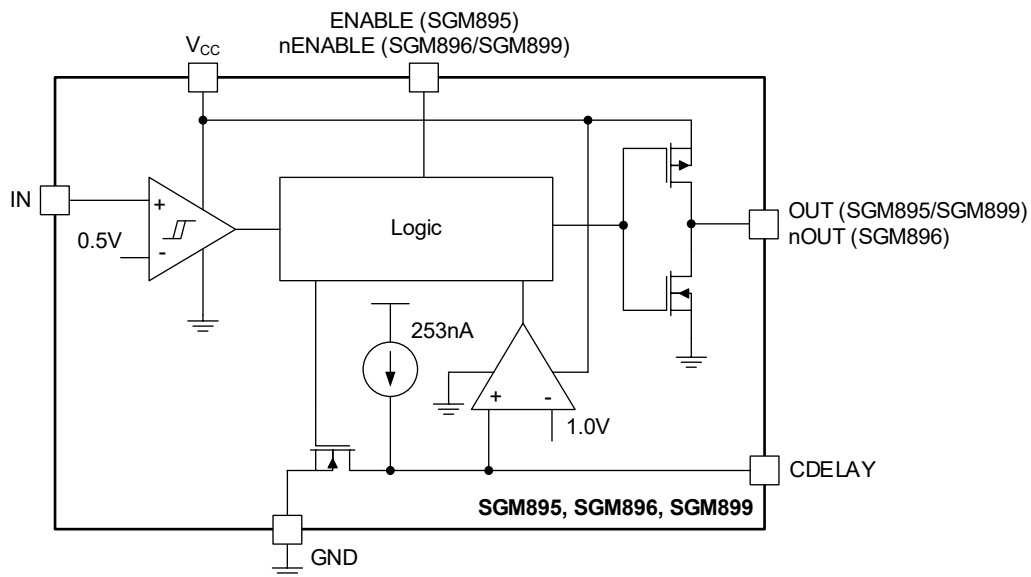
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

$V_{CC} = 3.3V$  and  $T_J = +25^{\circ}C$ , unless otherwise noted.





**FUNCTIONAL BLOCK DIAGRAM**



**Figure 2. SGM895/SGM896/SGM899 Block Diagram**

**DETAILED DESCRIPTION**

The SGM895/SGM896/SGM897/SGM898/SGM899 are low-power and high-accuracy microprocessor supervisory circuits with adjustable sequencing capability.

When  $V_{IN}$  exceeds  $V_{TH}$ , set enable input to assert or deassert output. After the enable input is asserted, the output asserts with the CDELAY adjusted delay period (SGM89\_A) or with a 350ns fixed propagation delay (SGM89\_P). The output pin states of all devices are based on various  $V_{IN}$  and enable input shown in Table 1, 2, and 3.

**Table 1. SGM895/SGM897 Output**

IN Pin	ENABLE Pin	OUT Pin
$V_{IN} < V_{TH}$	Low	Low
$V_{IN} < V_{TH}$	High	Low
$V_{IN} > V_{TH}$	Low	Low
$V_{IN} > V_{TH}$	High	OUT = $V_{CC}$ (SGM895)
		OUT = high-impedance (SGM897)

**Table 2. SGM896/SGM898 Output**

IN Pin	nENABLE Pin	nOUT Pin
$V_{IN} < V_{TH}$	Low	nOUT = $V_{CC}$ (SGM896)
		nOUT = high-impedance (SGM898)
$V_{IN} < V_{TH}$	High	nOUT = $V_{CC}$ (SGM896)
		nOUT = high-impedance (SGM898)
$V_{IN} > V_{TH}$	Low	Low
$V_{IN} > V_{TH}$	High	nOUT = $V_{CC}$ (SGM896)
		nOUT = high-impedance (SGM898)

**Table 3. SGM899 Output**

IN Pin	nENABLE Pin	OUT Pin
$V_{IN} < V_{TH}$	Low	Low
$V_{IN} < V_{TH}$	High	Low
$V_{IN} > V_{TH}$	Low	High
$V_{IN} > V_{TH}$	High	Low

**Supply Voltage Input ( $V_{CC}$ )**

The  $V_{CC}$  voltage range is from 1.6V to 5.5V, When  $V_{CC}$  falls below  $V_{UVLO}$ , the device deasserts. However, the output state is not guaranteed if  $V_{CC}$  is lower than 1.2V. For noisy systems, it is recommended to place a 100nF bypass capacitor close to the  $V_{CC}$  pin. A 100kΩ pull-down resistor should be connected to ground for push-pull output device to ensure correct logic low state.

**Detection Input (IN)**

IN pin is used to monitor external voltage, with low leakage current, and larger-value resistive divider will not cause significant bias voltage. The rising threshold  $V_{TH}$  is 0.5V and falling threshold  $V_{TL}$  is 0.495V ( $V_{HYST} = 5mV$ ). Refer to Table 1, 2 and 3. With asserted ENABLE/nENABLE pin, when  $V_{IN}$  is above  $V_{TH}$ , OUT goes high (nOUT goes low) after a  $t_{DELAY}$  period. When  $V_{IN}$  falls below 0.495V, OUT goes low (nOUT goes high) after a delay time of 50μs.

**Adjustable Delay (CDELAY)**

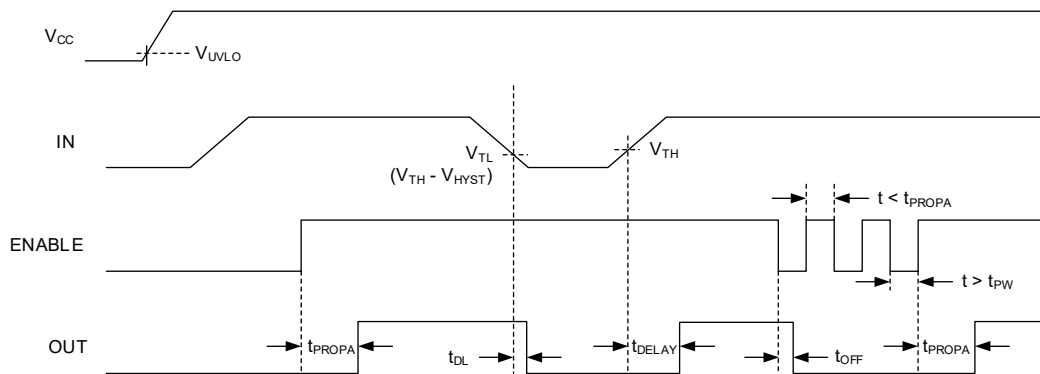
An external capacitor connected between CDELAY pin and GND is used to adjust delay time. With asserted ENABLE/nENABLE pin, when  $V_{IN}$  is above  $V_{TH}$ , the internal current  $I_{CD}$  is 253nA (TYP). The current source starts charging capacitor to 1V, OUT goes high (nOUT goes low), and the capacitor is immediately discharged to ensure next  $t_{DELAY}$  period. Adjust the delay time according to the equation:

$$t_{DELAY} (ms) = 3.95 \times C_{CDELAY} (nF) + 0.048ms \quad (1)$$

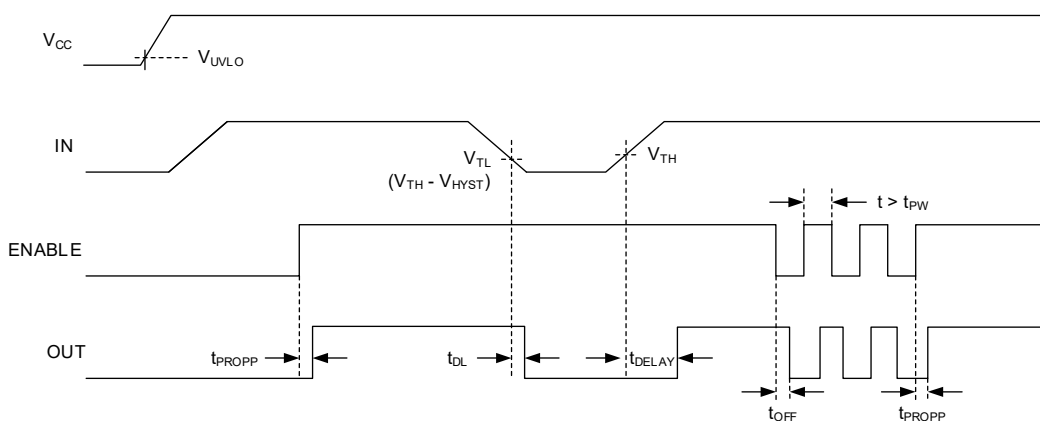
where  $C_{CDELAY}$  is the external capacitor from CDELAY to GND.

Under the condition of  $V_{IN} > V_{TH}$ , the output state depends on the state of ENABLE (nENABLE). For devices SGM89\_A, the delay time can be adjusted by external capacitor. For devices SGM89\_P, the propagation delay is fixed ( $t_{OFF} = 350ns$ ). Timing diagrams of all devices are shown in Figure 3 to Figure 8.

**DETAILED DESCRIPTION (continued)**

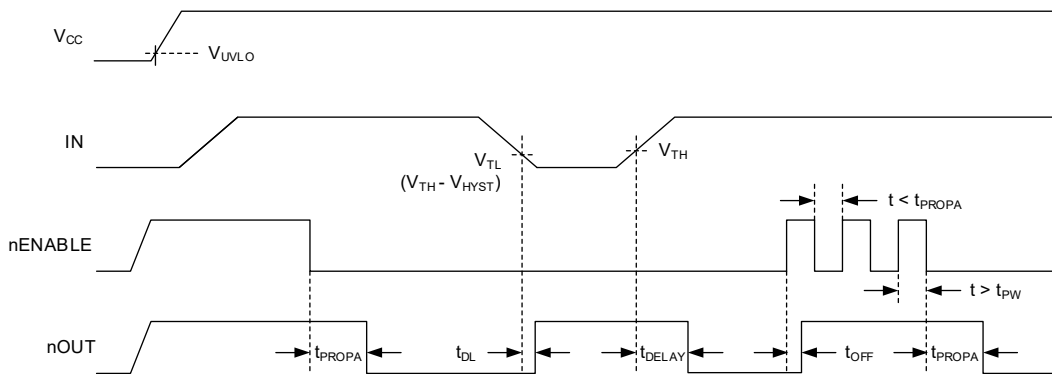


**Figure 3. SGM895A/SGM897A Timing Diagram**

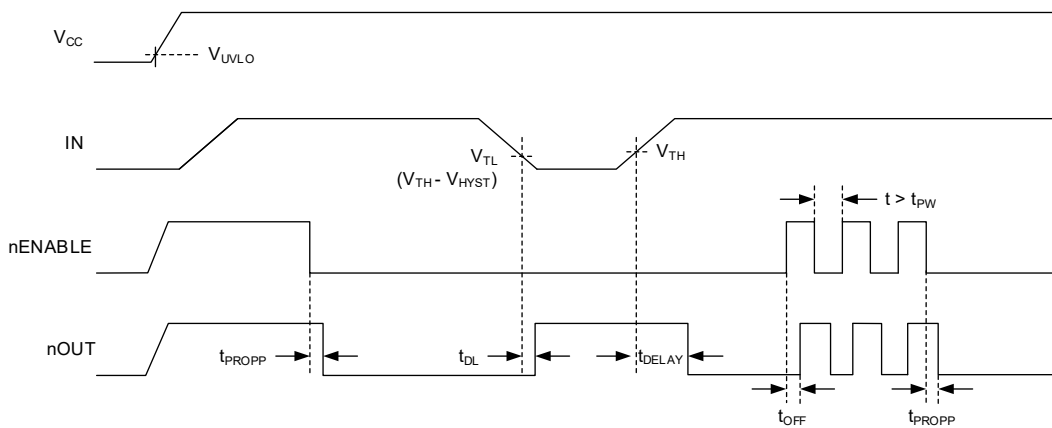


**Figure 4. SGM895P/SGM897P Timing Diagram**

**DETAILED DESCRIPTION (continued)**

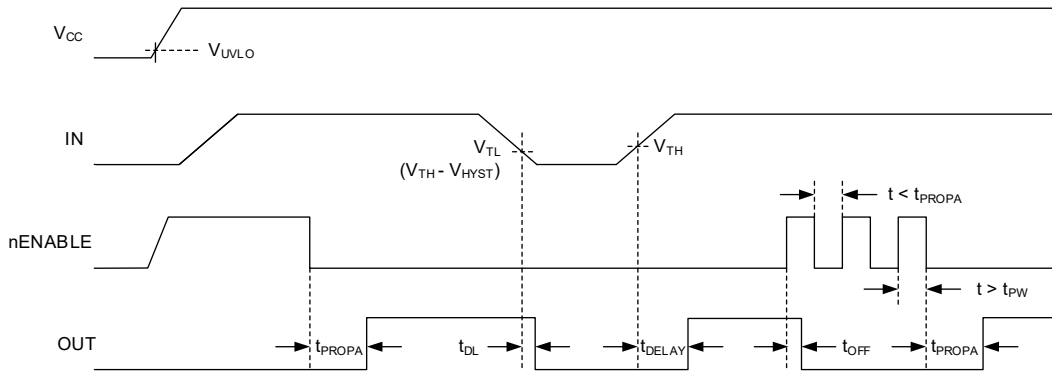


**Figure 5. SGM896A/SGM898A Timing Diagram**

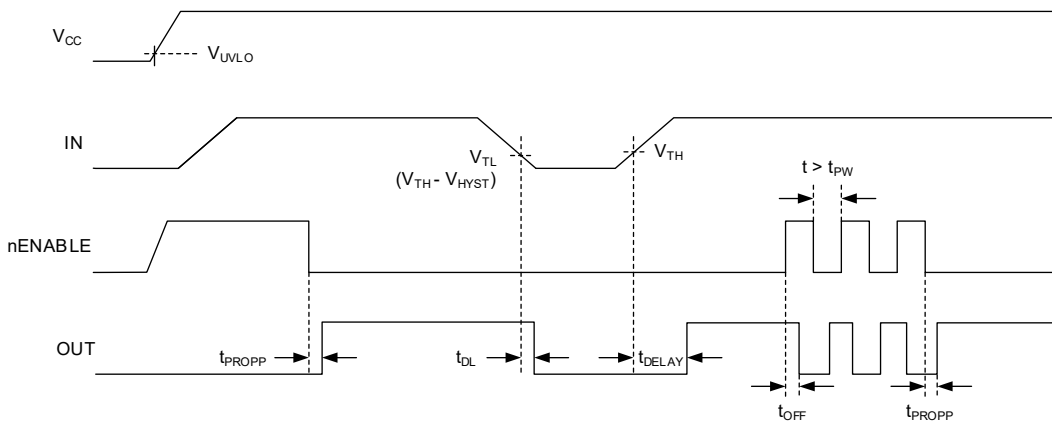


**Figure 6. SGM896P/SGM898P Timing Diagram**

**DETAILED DESCRIPTION (continued)**



**Figure 7. SGM899A Timing Diagram**



**Figure 8. SGM899P Timing Diagram**

**Enable Input (ENABLE or nENABLE)**

When  $V_{IN}$  is above  $V_{TH}$ , two types enable input ENABLE/nENABLE determine the output state. The SGM895/SGM897 are active-high enable input and SGM896/SGM898/SGM899 are active-low enable input. For devices SGM89\_A, the delay time can be adjusted by an external capacitor. For devices SGM89\_P, the propagation delay is fixed of 350ns.

The maximal logic-low threshold  $V_{IL}$  is 0.4V and minimal logic-high threshold  $V_{IH}$  is 1.4V.

**Output (OUT/nOUT)**

There are four selectable output options. The SGM895/SGM899 are active-high, push-pull output. the SGM897 is active-high, open-drain output. the SGM896 is active-low, push-pull output. And the SGM898 is active-low, open-drain output. The reference voltage of push-pull outputs are  $V_{CC}$ , and the pull-up reference voltage of open-drain outputs are up to 28V.

**APPLICATION INFORMATION**

**Input Threshold**

IN pin can be used to monitor external voltage through resistive divider. With low leakage current, larger-value resistors reduce current consumption without significant bias voltage. According to typical application circuit in Figure 1, for a given R<sub>2</sub>, R<sub>1</sub> can be calculated based on desired detection voltage through the following equation:

$$R_1 = R_2 \times \left[ \frac{V_{MONITOR}}{V_{TH}} - 1 \right] \tag{2}$$

V<sub>MONITOR</sub> is the desired detection voltage. V<sub>TH</sub> is the detector input threshold of 0.5V.

**Pull-Up Resistor Values (SGM897/SGM898)**

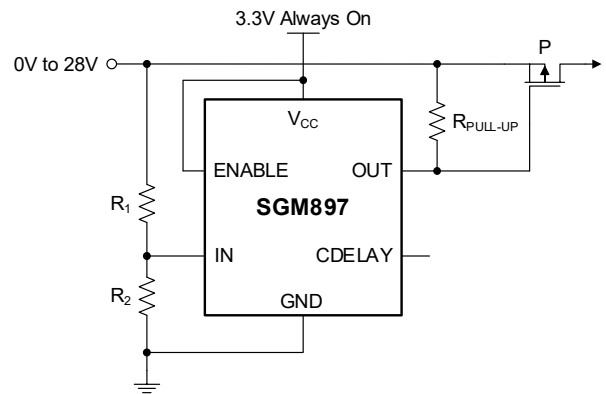
To ensure proper output logic-low voltage, pull-up resistor value should be limited. Refer to Electrical Characteristics section, if V<sub>CC</sub> is 2.25V, the pull-up voltage is 28V, and for an output voltage lower than 0.3V, the pull-up resistor should be limited to 56kΩ. if V<sub>CC</sub> is 4.5V and the pull-up voltage is 28V, and for an output voltage lower than 0.4V, the pull-up resistor should be limited to 28kΩ. The sink current ability depends on the V<sub>CC</sub> supply voltage.

**Typical Application Circuits**

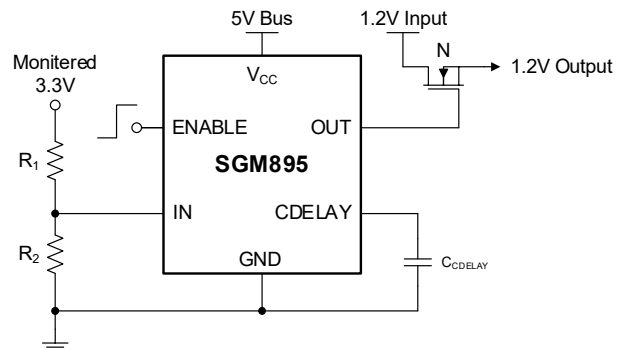
Three types typical applications are shown in Figure 9, 10 and 11. Figure 9 shows that the SGM897 is used as an over-voltage protection circuit by a P-channel MOSFET. Figure 10 shows that the SGM895 is used as a low-voltage sequencing with an N-channel MOSFET. Figure 11 shows that the SGM895 is used in a multiple-output sequencing circuit.

**Using an N-Channel Device for Sequencing**

In higher power applications, the power loss of N-channel MOSFET can be reduced due to its lower on-resistance. However, it requires a sufficient positive V<sub>GS</sub> voltage to fully turn on. Figure 10 shows the switch sequencing circuit by using an N-channel MOSFET. Up to 28V pull-up voltage provides sufficient V<sub>GS</sub> voltage for higher voltage applications.

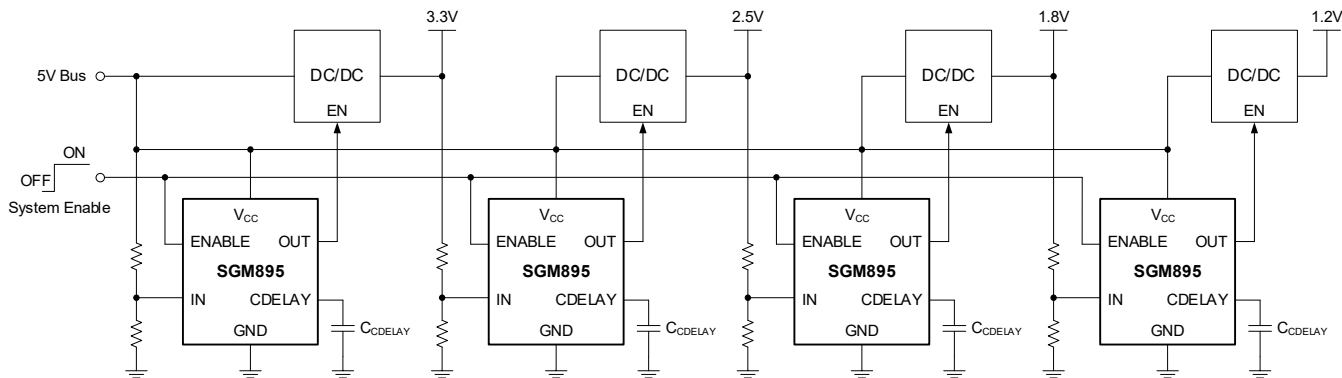


**Figure 9. Over-Voltage Protection**



**Figure 10. Low-Voltage Sequencing Using an N-Channel MOSFET**

**APPLICATION INFORMATION (continued)**



**Figure 11. Multiple-Output Sequencing**

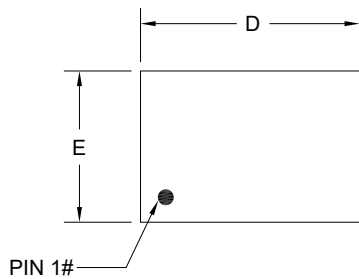
**REVISION HISTORY**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

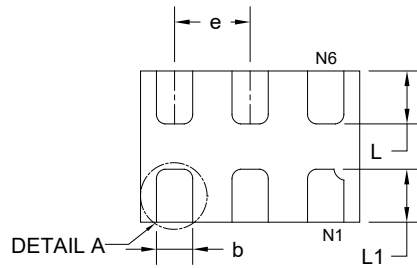
	Page
<b>MAY 2023 – REV.A.3 to REV.A.4</b>	
Changed Electrical Characteristics Section.....	6
Updated Detail Description section.....	10-13
Updated Application Information section.....	14, 15
<b>OCTOBER 2021 – REV.A.2 to REV.A.3</b>	
Updated Package Outline Dimensions section .....	10, 11
<b>OCTOBER 2021 – REV.A.1 to REV.A.2</b>	
Updated UTDFN-1.45×1-6AL Package.....	4, 16
<b>JULY 2021 – REV.A to REV.A.1</b>	
Changed Package/Ordering Information section.....	2
<b>Changes from Original (JULY 2020) to REV.A</b>	
Changed from product preview to production data.....	All

PACKAGE OUTLINE DIMENSIONS

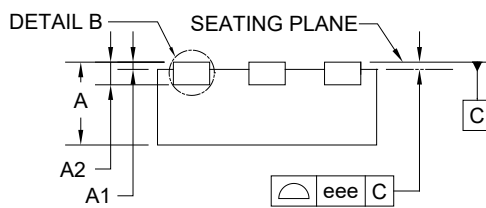
UTDFN-1.45×1-6AL



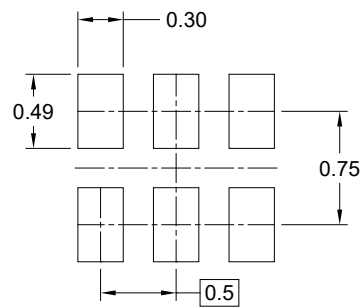
TOP VIEW



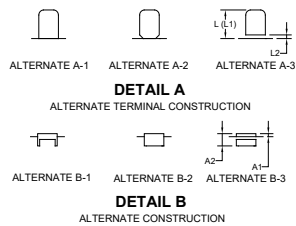
BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN (Unit: mm)



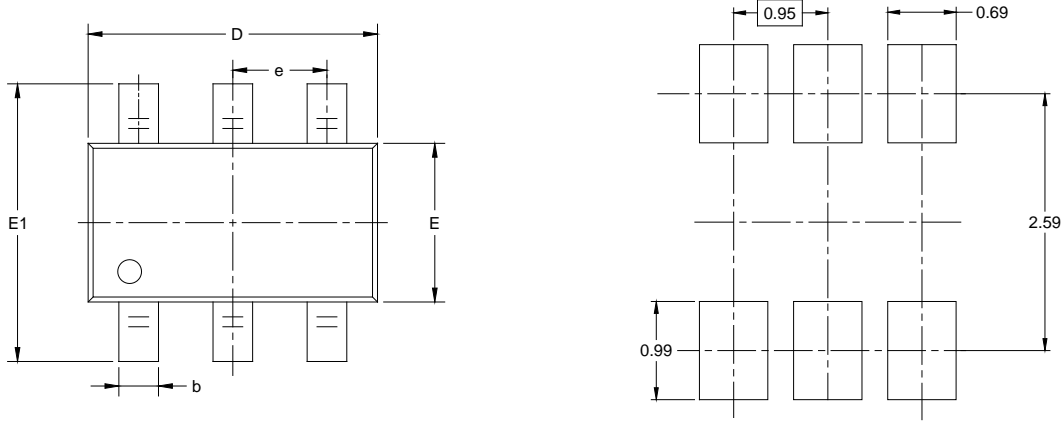
Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	0.450	-	0.600
A1	-0.004	-	0.050
A2	0.150 REF		
b	0.150	-	0.300
D	1.374	-	1.526
E	0.924	-	1.076
e	0.500 BSC		
L	0.250	-	0.450
L1	0.250	-	0.500
L2	0.000	-	0.100
eee	0.050		

NOTE: This drawing is subject to change without notice.

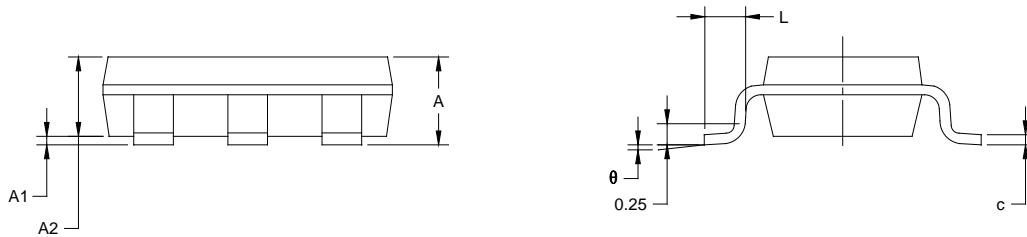


## PACKAGE OUTLINE DIMENSIONS

### TSOT-23-6



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	-	-	1.100
A1	0.000	-	0.100
A2	0.700	-	1.000
b	0.300	-	0.500
c	0.080	-	0.200
D	2.820	-	3.050
E	1.550	-	1.700
E1	2.650	-	2.950
e	0.950 BSC		
L	0.300	-	0.600
θ	0°	-	8°

NOTES:

1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
UTDFN-1.45×1-6AL	7"	9.5	1.15	1.60	0.75	4.0	4.0	2.0	8.0	Q1
TSOT-23-6	7"	9.5	3.20	3.10	1.10	4.0	4.0	2.0	8.0	Q3

DD0001

# PACKAGE INFORMATION

## CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18

DD0002